

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Li-Ken YEH</td><td>08/24/2007</td></tr><tr><td>I-Hsiang CHIU</td><td>08/24/2007</td></tr></tbody></table>	Name	Execution Date	Li-Ken YEH	08/24/2007	I-Hsiang CHIU	08/24/2007			
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RECEIVING PARTY DATA									
<table border="1"><tr><td>Name:</td><td>MEMSmart Semiconductor Corp.</td></tr><tr><td>Street Address:</td><td>10 F, No. 255, Minsheng Rd., East Dist.</td></tr><tr><td>City:</td><td>Hsinchu City</td></tr><tr><td>State/Country:</td><td>TAIWAN</td></tr></table>	Name:	MEMSmart Semiconductor Corp.	Street Address:	10 F, No. 255, Minsheng Rd., East Dist.	City:	Hsinchu City	State/Country:	TAIWAN	
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PROPERTY NUMBERS Total: 1									
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>11845780</td></tr></tbody></table>	Property Type	Number	Application Number:	11845780					
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CORRESPONDENCE DATA									
Fax Number: (361)579-9966 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone: 3614859179									
Email: bs@pat-bangshia.com									
Correspondent Name: BANGER SHIA									
Address Line 1: 204 CANYON CREEK									
Address Line 4: VICTORIA, TEXAS 77901									
ATTORNEY DOCKET NUMBER:	CFP-3871 (C-269)								
NAME OF SUBMITTER:	BANGER SHIA								
Total Attachments: 3 source=CFP_3871_ASSIGN_1#page1.tif source=CFP_3871_ASSIGN_2#page1.tif source=CFP_3871_ASSIGN_3#page1.tif									

OP \$40.00 11845780

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PATENT
REEL: 019751 FRAME: 0308

ASSIGNMENT DEED

ASSIGNOR:

Li-Ken YEH

10F., No.255, Minsheng Rd., East District,
Hsinchu City 30043 Taiwan, R.O.C.

I-Hsiang CHIU

10F., No.255, Minsheng Rd., East District,
Hsinchu City 30043 Taiwan, R.O.C.

ASSIGNEE:

MEMSmart Semiconductor Corp.

10F., No.255, Minsheng Rd., East District,
Hsinchu City 30043 Taiwan, R.O.C.

Whereas, Li-Ken YEH / I-Hsiang CHIU

whose address is set forth above (hereinafter referred to as "Assignor", consideration of payment to it of the sum of Ten U.S. Dollars (U.S.\$10.00) and for other good and valuable consideration, receipt and sufficiency of which are acknowledged hereby; received from

MEMSmart Semiconductor Corp., whose address is set forth above (hereinafter referred to as "Assignee");

Assignor has sold, assigned, and conveyed and hereby does evidence such sale, assignment and conveyance unto said Assignee, its successors and/or assigns, Assignor's entire right, title and interest —

(1) In and to an invention entitled _____
MICROELECTROMECHANICAL SYSTEM AND PROCESS OF MAKING
THE SAME
as described in United States Patent Application Serial No. _____, filed on
_____; which issued into United States Letters Patent No.
_____ on _____, including the right to recover for
past infringements thereof.

(2) In and to said Application for Letters Patent and said Letters Patent No.
_____ which issued _____ on said Application and any and
all other applications for letters patent of the United States of America (including renewal,
divisional, continuation, continuation-in-part, substitute and reissue applications) based upon
said invention, including extensions and reissues, if any, to the full ends of the terms for
which said Letters Patent of the United states has been granted.

(3) In and to all applications for said invention, now or hereafter filed in countries
foreign to the United States of America, and in and to any and all letters patent granted on
said applications to the full ends of the terms for which said Letters Patent may be granted.

Assignor further covenants and agrees that it has not executed and will not execute any
documents in conflict herewith, and it further agrees that it will at any time upon request by
Assignees execute and deliver any and all papers that may be necessary or desirable to perfect
title to said invention, Application for Letters Patent, and the Letters Patent to Assignees, and
if Assignees desires to file one or more divisional, continuation, continuation-in-part, or
substitute applications of or for said Letters Patent of the United States of America, or to
secure a reissue or extension of such Letters Patent, or to file a disclaimer relating thereto,
Assignors will upon request by Assignees sign all papers, make all rightful oaths and do all
lawful acts requisite of it for such reissue or extension, or the procuring thereof, and for the
filing of such disclaimer, but at the expense of Assignees, its successors and/or assigns.

Assignor further agrees that it will at any time upon request by Assignee communicate
to Assignee any facts relating to said invention and Letters Patent or the history thereof, know
to Assignor and cause its agent(s) to testify to the same in any interference or any litigation
when requested so to do by Assignee.

And the Commissioner of Patents and Trademarks of the United States of America and comparable officials in countries foreign to the United States of America to record and/or issue said Letters Patent, and the like to Assignee as assignee of Assignor's entire right, title and interest therein.

Signed at Hsinchu Taiwan this 24 day of August 2007.

Assignor:

By : Li-Ken Yeh I-Hsiang Chiu

Name: Li-Ken YEH

I-Hsiang CHIU

Title : Inventor

Inventor

Date : August 24, 2007

August 24, 2007

Witness:

Signature: _____

Name :

Address :

Date: